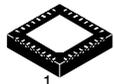


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

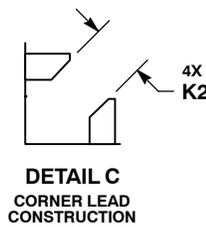
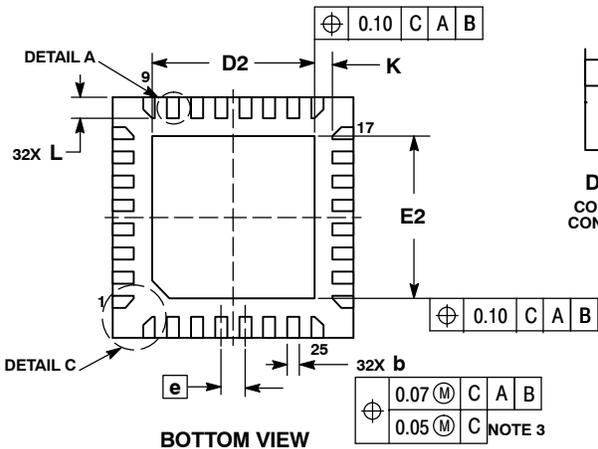
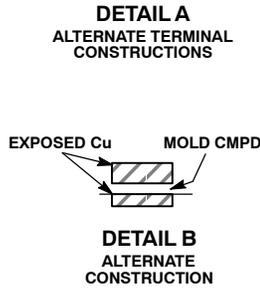
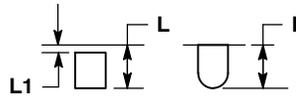
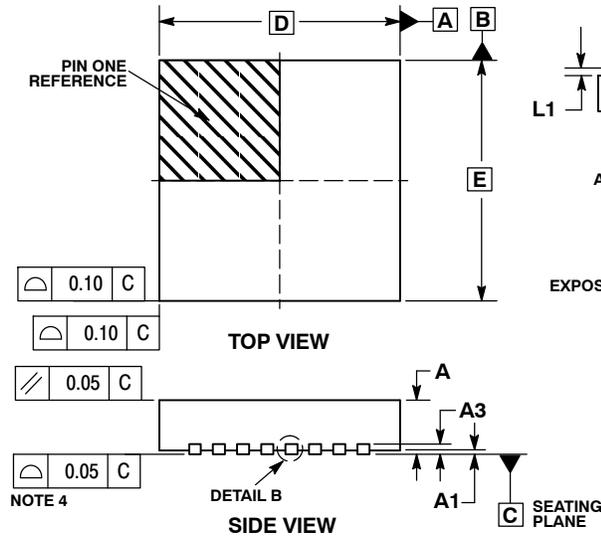
ON Semiconductor®



SCALE 2:1

QFN32 4x4, 0.4P
CASE 485CD
ISSUE A

DATE 09 OCT 2012

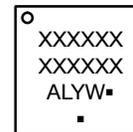


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	4.00 BSC	
D2	2.60	2.80
E	4.00 BSC	
E2	2.60	2.80
e	0.40 BSC	
K	0.30 REF	
K2	0.45 REF	
L	0.25	0.45
L1	---	0.15

GENERIC MARKING DIAGRAM*

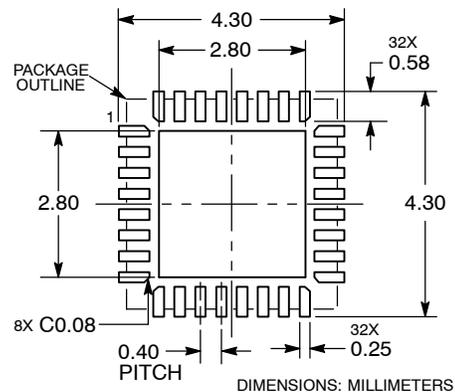


- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

RECOMMENDED MOUNTING FOOTPRINT



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NEW STANDARD:		
DESCRIPTION:	QFN32 4X4, 0.4P	PAGE 1 OF 2

